

# **HTPA16x16dR2L2.1/0.8F5.0**

**Datasheet for Thermopile Array Sensor with Lens Optic**

## **DISCLAIMER**

We reserve the right to correct or update the content, technical specifications or product descriptions at any time without prior notification.

All information is provided "as is", without any warranty, express or implied, including but not limited to warranties of merchantability or fitness for a particular purpose.

To ensure you are using the most up-to-date and accurate version, please always refer to the latest edition available on our official website.

Only the version published on the website shall be considered authoritative and current.

## Content

Changelog .....	3
1 Cleaning and Handling of Sensors with Optical Elements.....	4
2 Principal Schematic for HTPA16x16d .....	6
3 Pin Assignment – Bottom View .....	6
4 Optical Orientation.....	7
5 Order Code Example.....	8
6 Application Note.....	9
7 Serial Order of Frame .....	10
8 Characteristics.....	11
8.1 Common Specifications .....	11
8.2 Optical Characteristics .....	11
9 Electric Specifications.....	12
10 I <sup>2</sup> C Timings HTPA16x16d .....	13
11 I <sup>2</sup> C Communication .....	14
11.1 Write Command .....	14
11.2 Read Command .....	14
11.3 Sensor Commands.....	14
11.4 EEPROM Commands .....	18
11.5 I <sup>2</sup> C Example Sequences – EEPROM Wakeup / Standby.....	19
11.6 I <sup>2</sup> C Example Sequences – EEPROM Block Erase / Block Write .....	19
11.7 I <sup>2</sup> C Example Sequences – EEPROM Sequential Erase/Write .....	20
11.8 I <sup>2</sup> C Example Sequence – EEPROM Continuous Erase .....	21
11.9 I <sup>2</sup> C Example Sequence – EEPROM Continuous Write .....	21
11.10 I <sup>2</sup> C Example Sequence – EEPROM Sequential Read.....	22
11.11 I <sup>2</sup> C Example Sequence – EEPROM Continuous Read.....	22
11.12 I <sup>2</sup> C Example Sequence – Init and Read Thermopile Array .....	23
12 Temperature Calculation.....	24
12.1 Ambient Temperature .....	25
12.2 Thermal Offset.....	26
12.3 Electrical Offset .....	26
12.4 VDD Compensation.....	27
12.5 Object Temperature .....	28
13 Example Calculation .....	29
13.1 Example Look-up Table.....	30
14 Order Code Chart.....	32
15 Outer Dimension.....	33

## Changelog

2019-01-10	Added accuracy; erase of default values for TRIM registers
2019-02-28	Added handling advice
2019-03-20	Added allowed pixelmask
2019-09-30	Initial implementation of 16x16dR2L1.6 sensor
2019-11-22	Small corrections for L1.6 datasheet
2019-12-05	Small corrections for L1.6 datasheet
2020-05-11	Revised soldering recommendation to non-SMD
2020-09-05	Stack buffer recommendation; how to dK in °C
2021-01-30	Order code; change note implementation; correction VDD formula
2021-08-12	New order code
2021-12-14	Initial implementation of 16x16dR2L1.0 and L5.0 in Hi and UHi variant
2022-12-12	Updated drawing for 16x16R2L5.0UHiS
2023-02-08	EEPROM communication flow corrected
2023-02-13	Added radiometric radius for 16x16dR2L1.0
2024-12-18	Updated graphic for optical orientation
2025-01-31	Updated order code, added order code chart w/ available options
2025-03-17	Corrected Field of View for L1.6
2025-04-08	Corrected pin allocations
2025-08-18	Corrected graphic for pixel orientation
2025-10-16	Added max. measurable temperature
2025-11-18	Corrected accuracy specification
2025-03-02	Added calculation formula for CLK_Trim Register

# 1 Cleaning and Handling of Sensors with Optical Elements

## Cleaning of Filter with Isopropyl Alcohol or Acetone

This is the method most universally used for cleaning optical elements with or without coatings. Filters or lenses mounted in our sensors may be cleaned rubbing the surfaces lightly with a clean, soft, all-cotton cloth or cotton swab during immersion in solvent or simply moistened with the solvent. The parts are then immediately wiped dry with another clean, soft, all-cotton cloth or cotton swab.

## Cleaning with Detergent and Water

A very mild, non-abrasive detergent (one which does not contain additives) and water may also be used for cleaning optical elements. In general, a detergent and water mixture is an excellent method for removing fingerprints and other smudges. The liquid detergent is first mixed with deionized water (proportions recommended by the manufacturer should be followed). The element is then washed, rinsed and immediately wiped dry. Use a clean, soft cloth when cleaning and drying. If the part is allowed to dry in air, a permanent stain may result.

Please note:

- Do not use isopropyl alcohol or acetone or detergent if the elements will be mounted in an assembly with a finish which may be soluble by these solvents.
- Please avoid glass isolation being moistened by solvent.
- If the part is allowed to dry in air, a permanent stain may result.

## Handling Advice

Sensors with optical elements deserve special consideration in their handling and care. Ordinarily, filters or lenses are cleaned and inspected prior to shipment. If proper care is exercised during handling cleaning should not be necessary prior to use.

- Wear gloves when handling a sensor or optical element. Lightweight nylon or cotton gloves, which are relatively lint-free are recommended.
- Avoid touching the surface of filters and lenses.
- Protect devices from static discharge and static fields.
- Thermopile sensors are electrostatic sensitive devices. Sensors should be handled over an electrostatic protected work area.
- Precautions should be taken to avoid reverse polarity of power supply for sensors with integrated signal processing. Reversed polarity of power supply results in a destroyed unit.
- Sensors should rest preferably in a partitioned container where the mounted filters or lenses will be not coming into contact with other material.
- During storage optical surfaces should be covered to avoid contamination from the surrounding environment.

- A covered container can eliminate damage during transportation and storage.
- Sensors or optical elements should be stored in a restricted access area to eliminate handling.
- Do not expose the sensors to aggressive detergents such as freon, trichlorethylen, etc.
- Avoid rotating the sensors when they are soldered into a PCB or something similar.
- Shortening of the pins is not suggested. This may cause cracks in the glass of the pins and result in a leakage.
- If this is necessary, a tool for this is recommended. Please contact Heimann Sensor for further information.

### Soldering Recommendations

**Attention:** For all of our array sensors we give no guarantee on the calibration and its performance if the pins are shortened by the customer. Additionally, **we strongly recommend to not solder the sensor with its backplate directly to a PCB.** This will cause different thermal conductivity compared to air and the measurement results could get worse. **Use a minimum gap between PCB and backplate of 2 mm or more.** The glass of the pins to the back plate can get damage by applying high temperatures (during soldering), which will lead into a lower temperature reading what cannot be repaired afterwards.

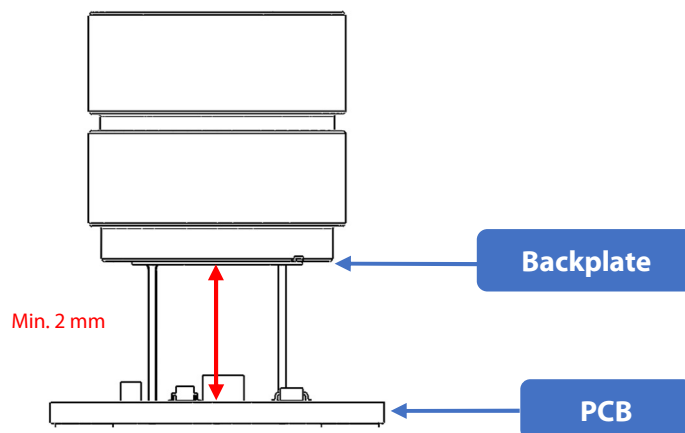


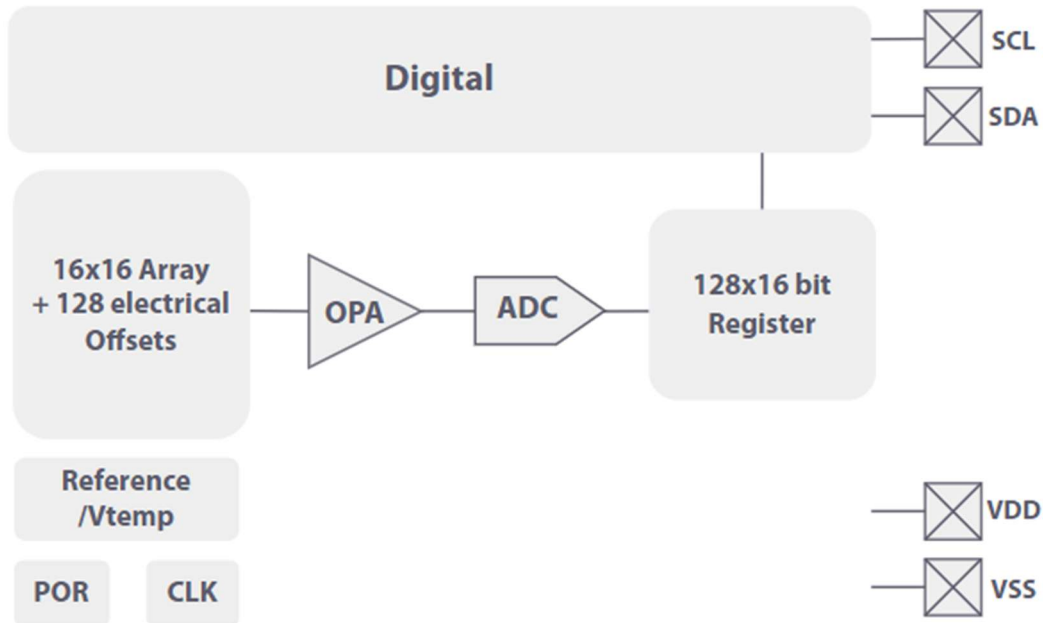
Figure 1: Soldering height

### Manual Iron Soldering and Automatic Point-to-Point Iron Soldering

Manual Iron Soldering and Automatic Point-to-Point Iron Soldering methods are allowed for TO packages. It is recommended for through hole applications to shield the package body from soldering heat by PCB or similar.

The soldering iron temperature should be set as low as possible (maximum 350 °C) and should not exceed recommended soldering time (maximum 3 seconds). The minimum distance between the housing body and the liquid solder should be at least 1.5 mm for 350 °C. Reflow soldering is not recommended.

## 2 Principal Schematic for HTPA16x16d



## 3 Pin Assignment – Bottom View

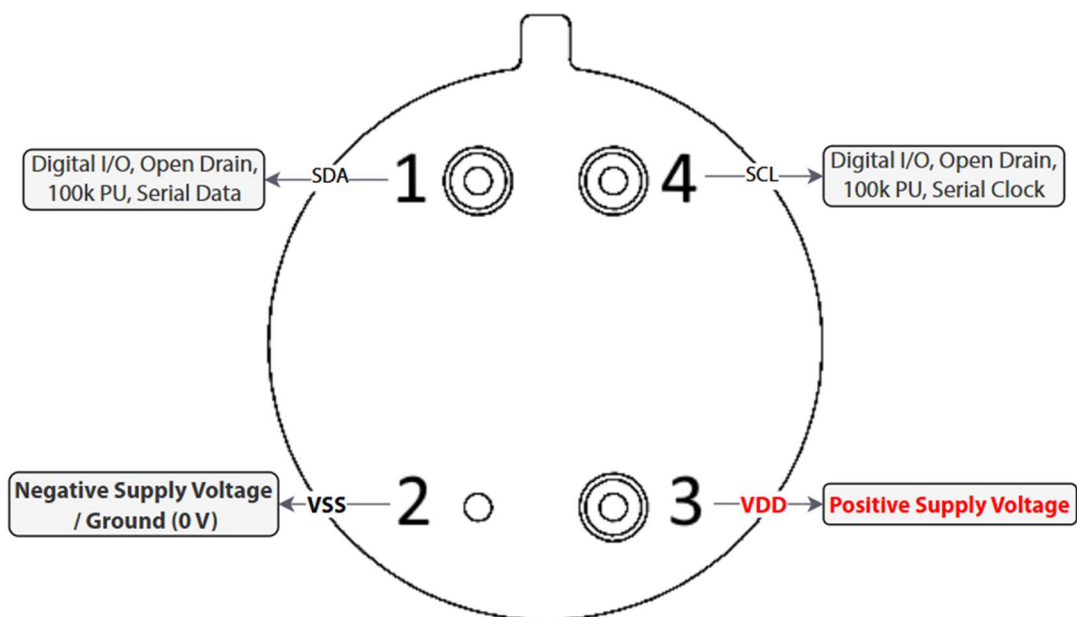
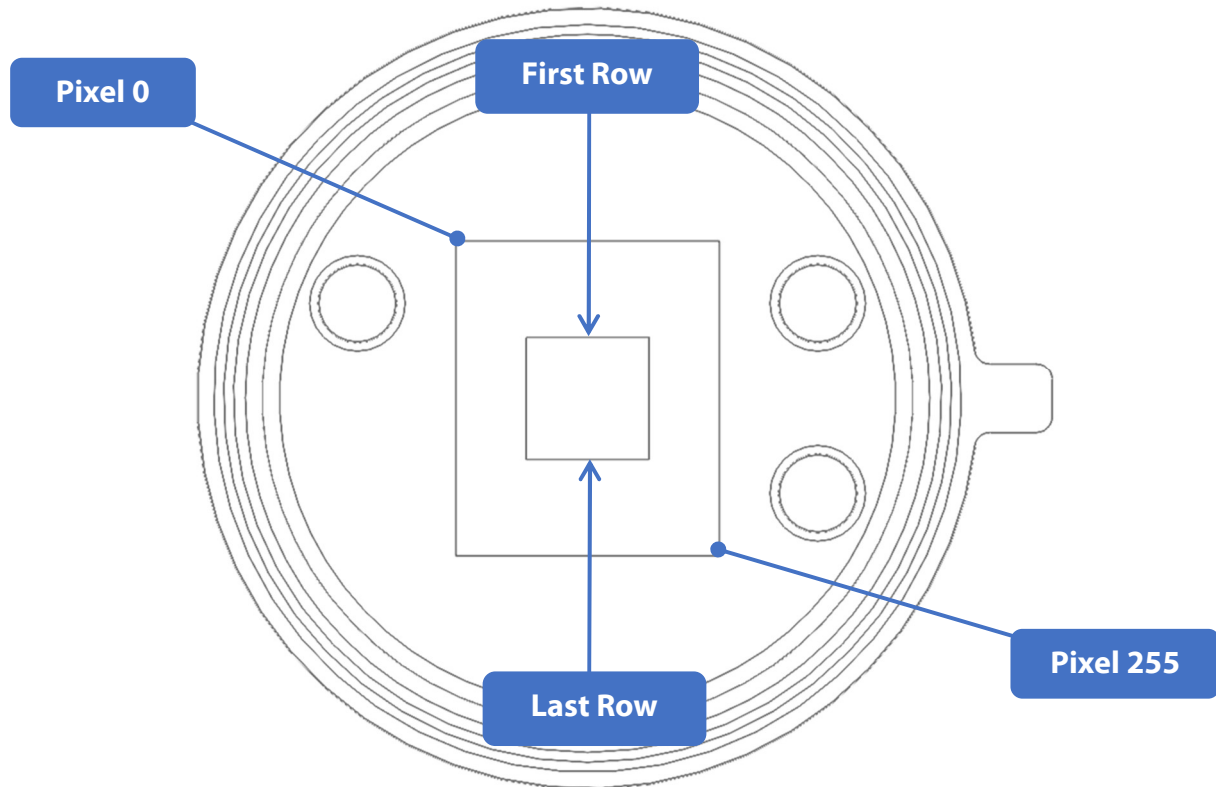
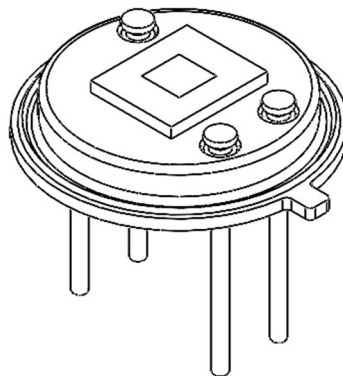


Figure 2: Pin-allocation

## 4 Optical Orientation



This illustration shows the pixel orientation after mirroring through the lens.



## 5 Order Code Example

HTPA32x32d	R2	L5.0/0.85	F7.7	e	Hi	M	(UDP)
1	2	3	4	5	6	7	8

		Description
1	Sensor Type	TP Array with 32x32 Pixel  For all available HTPA and module combinations contact our support
2	Revision	Silicon revision 2
3	Optics	Focal length/F-Number  Focal length: L5.0 = 5.0 mm F-Number: 0.85
4	Filter	F: Filter characteristics Not declared: Broadband AR Coating
5	External Aperture	Not declared: without external aperture e: with external aperture
6	Sensitivity	UH: increased sensitivity Hi: default sensitivity Not declared: lower sensitivity (greater measurement range)
7	Version	A: Application Set: comes with GUI, housing, power supply C: Calibrated sensor M: Modul: HTPA sensor soldered to PCB, calibrated stream
8	Interface	UDP: Ethernet connection, CAT5 PoE: Power over Ethernet, CAT5* i <sup>2</sup> C: 4 Pin Connector* USB: Power and data via USB 2.0**  * Interface option is only available for modules (HiM) ** Interface option is only available for Application Set (HiA)

## 6 Application Note

A pull-up resistor of 4.7 kΩ for the I<sup>2</sup>C pins (SDA and SCL) is recommended. In addition, adding 100 nF and 47 μF are improving the stability of the supply voltage.

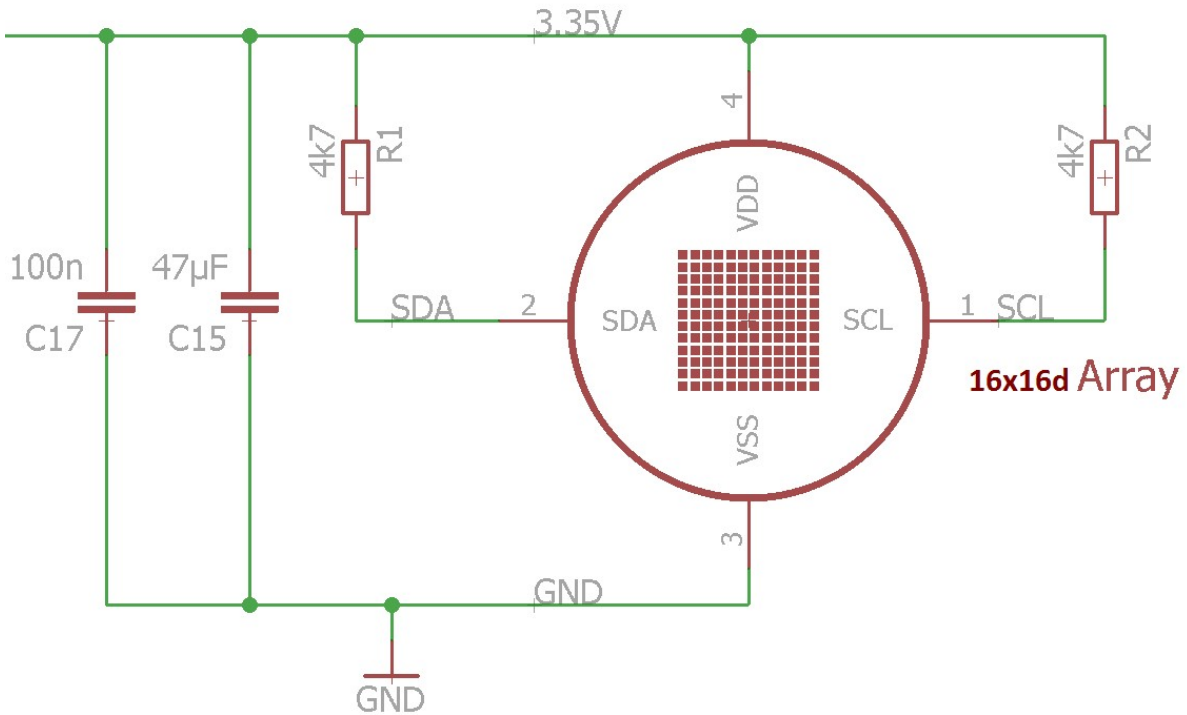


Figure 3: Recommended circuit for operation

The sensor can be powered directly via 3.35 V, if the supply voltage is stable enough, this has to be measured before and tested with the sensor. It is important to not insert any inductor or otherwise the noise will increase.

## 7 Serial Order of Frame

The sensor is divided into two parts (top and bottom half) which are again separated into 2 blocks. The readout order is shown below for the different blocks.

Block 0 (top)
Block 1 (top)
Block 1 (bottom)
Block 0 (bottom)

Figure 4: Division of blocks

Whenever a conversion is started the Block x of the top and bottom half are measured at the same time. Each block consists of 64 Pixel that are sampled fully parallel. The readout order on the bottom half is mirrored compared to the top half so that the central lines are always read last.

0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31
32	33	34	35	36	37	38	39	40	41	42	43	44	45	46	47
48	49	50	51	52	53	54	55	56	57	58	59	60	61	62	63
64	65	66	67	68	69	70	71	72	73	74	75	76	77	78	79
80	81	82	83	84	85	86	87	88	89	90	91	92	93	94	95
96	97	98	99	100	101	102	103	104	105	106	107	108	109	110	111
112	113	114	115	116	117	118	119	120	121	122	123	124	125	126	127
128	129	130	131	132	133	134	135	136	137	138	139	140	141	142	143
144	145	146	147	148	149	150	151	152	153	154	155	156	157	158	159
160	161	162	163	164	165	166	167	168	169	170	171	172	173	174	175
176	177	178	179	180	181	182	183	184	185	186	187	188	189	190	191
192	193	194	195	196	197	198	199	200	201	202	203	204	205	206	207
208	209	210	211	212	213	214	215	216	217	218	219	220	221	222	223
224	225	226	227	228	229	230	231	232	233	234	235	236	237	238	239
240	241	242	243	244	245	246	247	248	249	250	251	252	253	254	255

readout order top

readout order bottom

Figure 5: 16x16d readout order for active pixel

The electrical offsets are sampled in parallel for the top and bottom half. The matching rows for the corresponding electrical offsets and active Pixel are marked with the same color. The conversion of the electrical offsets is started by sending the command for the BLIND bit during the start command.

0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31
32	33	34	35	36	37	38	39	40	41	42	43	44	45	46	47
48	49	50	51	52	53	54	55	56	57	58	59	60	61	62	63
64	65	66	67	68	69	70	71	72	73	74	75	76	77	78	79
80	81	82	83	84	85	86	87	88	89	90	91	92	93	94	95
96	97	98	99	100	101	102	103	104	105	106	107	108	109	110	111
112	113	114	115	116	117	118	119	120	121	122	123	124	125	126	127

readout order top

readout order bottom

Figure 6: 16x16d readout order for electrical offset

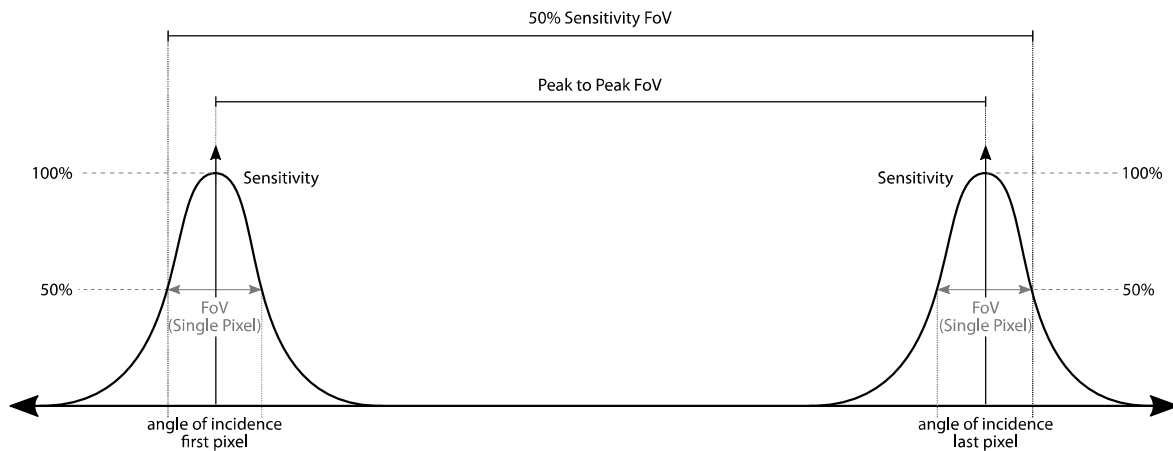
## 8 Characteristics

### 8.1 Common Specifications

Technology:	n-poly/p-poly Si
Element Resistance:	approx. 300 kOhms
Thermal pixel time constant:	<4 ms
Digital Interface:	I <sup>2</sup> C
EEPROM size:	1024 x 16-Bit
Pitch:	90 µm
Absorber size:	44 µm
Max. Framerate:	120 Hz
Max. measurable temperature:	500°C with default settings
(complete frame with maximum I <sup>2</sup> C and sensor clock speed and reduced ADC resolution)	
256 sensitive elements	

### 8.2 Optical Characteristics

Focal length:	2.1 mm ("L" equals the focal length of the lens)
F-Number:	0.8
Field of view:	44 x 44 deg. (50 % sensitivity FoV)



Lens coating:	LWP-Coating 5.0 Cut On (Tr. 5 %): 5.0 µm
---------------	---

Accuracy:	±3 % or ±3 K (whatever is larger) in the working ambient temperature range of 5° to 50 °C and object temperatures ≤ to 300 °C
-----------	---

## 9 Electric Specifications

Table 1: Absolute Maximum Ratings

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply Voltage	V <sub>DD</sub>		-0.3		3.6	V
Voltage at all inputs and outputs	V <sub>IO</sub>		-0.3		V <sub>DD</sub> +0.3	V
Storage Temperature	T <sub>STG</sub>		-40		85	Deg. C

Table 2: Operating Conditions

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply Voltage	V <sub>DD</sub>		3.3	3.35	3.6	V
Supply Current (sensor running)	I <sub>DD</sub>		3	3.9	4.8	mA
Supply Current (sensor in idle state)	I <sub>SBY</sub>		2.8	3.7	4.5	mA
Standby Current (sensor in sleep state)	I <sub>SBY</sub>		7	9	11	μA
Operation Temperature	T <sub>A</sub>		-20		65	Deg. C
ESD-Protection		Human body model	2			kV
		100pF + 1k50hm				

Table 3: Electrical Characteristics

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Digital Input						
Internal Clock frequency	F <sub>CLK</sub>		1	5	13	MHz
Internal I <sup>2</sup> C Pull up	R <sub>PU</sub>		1	100	100	kOhm
BIAS current	I <sub>BIAS</sub>		1	3	13	μA
BPA current	I <sub>BPA</sub>		0.2	1.5	4.0	μA
Input voltage high	V <sub>IH</sub>		0.7xV <sub>DD</sub>			V
Input voltage low	V <sub>IL</sub>				0.3xV <sub>DD</sub>	V
PTAT						
Temperature range			TBD		TBD	Deg. C
PTAT gradient				TBD		K/V

Table 4: Preamplifier / ADC

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Chopper frequency	F <sub>CHP</sub>			20		kHz
Preamplifier Noise	N <sub>PA</sub>	at 20 kHz		72		nV/Hz <sup>1/2</sup>
Frame rate (Full Array)	FR1			18		Hz
Frame rate (Half Array)	FR4			36		Hz
ADC pos. Reference	V <sub>REFP</sub>			1.6		V
ADC pos. Reference	V <sub>REFP</sub>			0.9		V
ADC resolution	ADC <sub>LSB</sub>	at 16-Bit		21		μV

## 10 I<sup>2</sup>C Timings HTPA16x16d

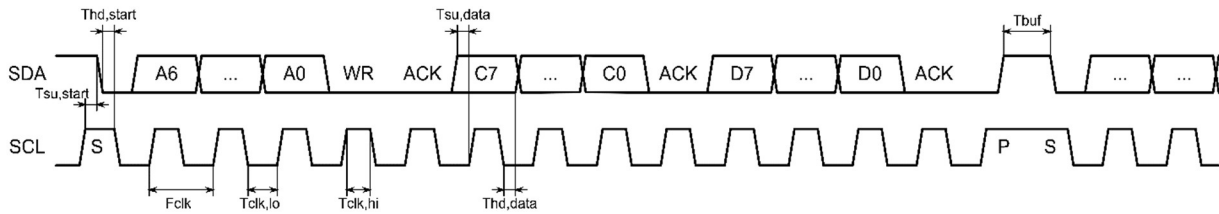


Figure 7: I<sup>2</sup>C Timings of HTPA16x16d

Table 5: I<sup>2</sup>C Timings

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
I <sup>2</sup> C clock frequency	F <sub>CLK</sub>			400	1000	kHz
low pulse duration	T <sub>CLK,lo</sub>		0.50			μs
high pulse duration	T <sub>CLK,hi</sub>		0.26			μs
data set up time	T <sub>SU,data</sub>		0.05			μs
data hold time	T <sub>hd,data</sub>		0.00			μs
start setup time	T <sub>SU,start</sub>		0.26			μs
start hold time	T <sub>hd,start</sub>		0.26			μs
stop setup time	T <sub>SU,stop</sub>		0.26			μs
Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
stop hold time	T <sub>hd,stop</sub>		0.26			μs
time between STOP / START	T <sub>buf</sub>		0.50			μs
Time startup (after Power-on Reset)	T <sub>startup</sub>				100	μs
Time wakeup (after sending WAKEUP)	T <sub>wakeup</sub>				80	μs

## 11 I<sup>2</sup>C Communication

The chip uses the 7-bit I<sup>2</sup>C address 0x1A for configuration and sensor data and the address 0x1B to access the internal EEPROM followed by 1-bit of read/write command. The address byte is followed by an 8-bit command.

### 11.1 Write Command

In case of a write access to an internal register the command is followed by the data byte. The chip acknowledges each byte with a low active ACK bit.

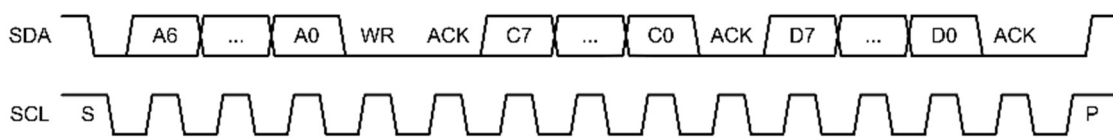


Figure 8: Write Command

### 11.2 Read Command

To read data from the chip first the address and command must be sent. After the last ACK a new start-bit (repeated start) and the address with a set read-flag initiates the read sequence. There can be bytes read as many as required. The last byte must be denoted by a not-acknowledge. The shown example below can be used e.g. to get the status register.

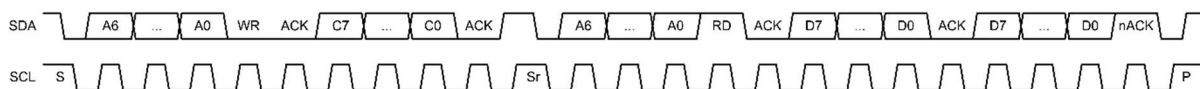


Figure 9: Read Command

### 11.3 Sensor Commands

The sensor has several registers that can be written and read, they are listed below.

Table 6: Configuration Register (write only)

Addr / CMD	0x1A (7-bit!)/ 0x01							
Config Reg	7	6	5	4	3	2	1	0
Name	RFU				START	VDD_MEAS	BLIND	WAKEUP
Default	0	0	0	0	0	0	0	0

The WAKEUP bit is used to switch on / off the chip and must be set prior all other operations. After the START bit is set the chip starts a conversion of the array or blind elements and enters the idle state (not sleep!) when finished.

If the BLIND bit is set the electrical offsets are sampled instead of the active pixel.

If VDD\_MEAS bit is set the VDD voltage is measured instead of the PTAT value.

RFU means reserved for future use and can be subject to change.

Table 7: Status Register (read only)

Addr / CMD	0x1A (7-bit!)/ 0x02							
Status Reg	7	6	5	4	3	2	1	0
Name	RFU							EOC
Default	0	0	0	0	0	0	0	0

If the EOC flag is set a previous started conversion has been finished.

Trim Register 1 (write only)

Addr / CMD	0x1A (7-bit!)/ 0x03							
Trim Reg 1	7	6	5	4	3	2	1	0
Name	RFU				MBIT TRIM			

REF\_CAL: selectable amplification

MBIT\_TRIM:  $m = 4$  to  $12 \Rightarrow (m+4)$  bit as ADC resolution

Trim Register 2 (write only)

Addr / CMD	0x1A (7-bit!)/ 0x04							
Trim Reg 2	7	6	5	4	3	2	1	0
Name	RFU				BIAS TRIM TOP			

BIAS\_TRIM\_TOP: 0 to 31  $\Rightarrow 1 \mu\text{A}$  to  $13 \mu\text{A}$

This setting is used to adjust the BIAS current of the ADC. A faster clock frequency requires a higher BIAS current setting.

Trim Register 3 (write only)

Addr / CMD	0x1A (7-bit!)/ 0x05							
Trim Reg 3	7	6	5	4	3	2	1	0
Name	RFU				BIAS TRIM BOT			

BIAS\_TRIM\_BOT: 0 to 31  $\Rightarrow 1 \mu\text{A}$  to  $13 \mu\text{A}$

This setting is used to adjust the BIAS current of the ADC. A faster clock frequency requires a higher BIAS current setting.

Trim Register 4 (write only)

Addr / CMD	0x1A (7-bit!)/ 0x06							
Trim Reg 4	7	6	5	4	3	2	1	0
Name	RFU				CLK TRIM			

CLK\_TRIM ranges from 0 to 63 and corresponds the clock frequency  $F_{CLK}$  which can be determined via the following formula:

$$F_{CLK} = \left( F_{CLK,min} + \frac{F_{CLK,max} - F_{CLK,min}}{63} \cdot \text{CLK\_TRIM} \right) \text{MHz}$$

with

$$F_{CLK,min} = 1 \text{ MHz}$$

$$F_{CLK,max} = 13 \text{ MHz}$$

The measure time depends on the clock frequency settings. One quarter frame takes about:

$$t_{fr4} = \frac{32 \cdot (2^{MBIT} + 4)}{F_{CLK}} \approx 27ms@5MHz$$

MBIT is equal to MBIT TRIM In Trim Register 1.

Trim Register 5 (write only)

Addr / CMD	0x1A (7-bit!) / 0x07							
Trim Reg 5	7	6	5	4	3	2	1	0
Name	RFU				BIAS TRIM TOP			

BPA\_TRIM\_TOP: 0 to 31 ⇒ 0.2 µA to 4.0 µA

This setting is used to adjust the common mode voltage of the preamplifier.

Trim Register 6 (write only)

Addr / CMD	0x1A (7-bit!) / 0x08							
Trim Reg 6	7	6	5	4	3	2	1	0
Name	RFU				BIAS TRIM BOT			

BPA\_TRIM\_BOT: 0 to 31 ⇒ 0.2 µA to 4.0 µA

This setting is used to adjust the common mode voltage of the preamplifier.

Trim Register 7 (write only)

Addr / CMD	0x1A (7-bit!) / 0x09							
Trim Reg 7	7	6	5	4	3	2	1	0
Name	PU SDA TRIM				PU SCL TRIM			

PU\_SDA\_TRIM: select internal pull up resistor on SDA (Default: 100 kOhm)

PU\_SCL\_TRIM: select internal pull up resistor on SCL (Default: 100 kOhm)

“1000” = 100 kOhm; “0100” = 50 kOhm; “0010” = 10 kOhm; “0001” = 1 kOhm

Table 8: Read Data 1 Command (Top Half of Array)

Addr / CMD	0x1A (7 Bit!) / 0x0A							
Read Data	7	6	5	4	3	2	1	0
1. Byte / 2. Byte	PTAT 1 MSB / LSB or VDD 1 MSB / LSB							
3. Byte / 4. Byte	Pixel (0+BLOCK*64) MSB / LSB							
5. Byte / 6. Byte	Pixel (1+BLOCK*64) MSB / LSB							
...	...							
129. Byte / 130. Byte	Pixel (63+BLOCK*64) MSB / LSB							

Table 9: Read Data 2 Command (Bottom Half of Array)

Addr / CMD	0x1A (7 Bit!) / 0x0B							
Read Data	7	6	5	4	3	2	1	0
1. Byte / 2. Byte	PTAT 2 MSB / LSB or VDD 2 MSB / LSB							
3. Byte / 4. Byte	Pixel (240-BLOCK*64) MSB / LSB							
5. Byte / 6. Byte	Pixel (241-BLOCK*64) MSB / LSB							
...	...							

<b>33. Byte / 34. Byte</b>	Pixel (255-BLOCK*64) MSB / LSB
<b>35. Byte / 36. Byte</b>	Pixel (224-BLOCK*64) MSB / LSB
<b>37. Byte / 38. Byte</b>	Pixel (225-BLOCK*64) MSB / LSB
...	
<b>65. Byte / 66. Byte</b>	Pixel (239-BLOCK*64) MSB / LSB
<b>67. Byte / 68. Byte</b>	Pixel (192-BLOCK*64) MSB / LSB
...	
<b>129. Byte / 130. Byte</b>	Pixel (207-BLOCK*64) MSB / LSB

The complete sensor data must be read at once. If the communication fails somewhere in between, all successive data will be corrupted. The readout can be stopped anywhere by pausing the clock. A new initialized readout proceeds at this stopped byte by continuing the clock, but the index is reset when a new conversion has been started.

If the bit for the electrical offsets (Bit 1 in Config 0x01) is set, the electrical offsets are sampled and can be read similar to the active pixel:

#### Read Data Electrical Offsets (Top Half of Array)

Addr / CMD	0x1A (7-bit!) / 0x0A							
Read Data	7	6	5	4	3	2	1	0
<b>1. Byte / 2. Byte</b>	PTAT 2 MSB / LSB or VDD 2 MSB / LSB							
<b>3. Byte / 4. Byte</b>	electrical offset (0) MSB / LSB							
<b>5. Byte / 6. Byte</b>	electrical offset (1) MSB / LSB							
...	...							
<b>129. Byte / 130. Byte</b>	electrical offset (63) MSB / LSB							

#### Read Data Electrical Offsets (Bottom Half of Array)

Addr / CMD	0x1A (7 Bit!) / 0x0B							
Read Data	7	6	5	4	3	2	1	0
<b>1. Byte / 2. Byte</b>	PTAT 2 MSB / LSB or VDD 2 MSB / LSB							
<b>3. Byte / 4. Byte</b>	electrical offset (112) MSB / LSB							
<b>5. Byte / 6. Byte</b>	electrical offset (113) MSB / LSB							
...	...							
<b>33. Byte / 34. Byte</b>	electrical offset (127) MSB / LSB							
<b>35. Byte / 36. Byte</b>	electrical offset (96) MSB / LSB							
...	...							
<b>129. Byte / 130. Byte</b>	electrical offset (79) MSB / LSB							

The complete sensor data must be read at once. If the communication fails somewhere in between, all successive data will be corrupted. The readout can be stopped anywhere by pausing the clock. A new initialized readout proceeds at this stopped byte by continuing the clock, but the index is reset when a new conversion has been started.

## 11.4 EEPROM Commands

To read/write data from/to the internal EEPROM the I2C address 0x1B is used.

### EEPROM Commands

Name	CMD	Read / Write	Comment
<b>Standby</b>	0x00	W	
<b>Active</b>	0x01	W	releases all signals to default state wait for 15µs when wake up from standby
<b>Normal Erase</b>	0x02	W	program pulse width 5ms
<b>Normal Write</b>	0x03	W	program pulse width 5ms
<b>Block Erase</b>	0x04	W	program pulse width 5ms
<b>Block Write</b>	0x05	W	program pulse width 5ms
<b>Normal Read</b>	0x06	W	program pulse width 5ms
<b>Set Address</b>	0x09	W	program pulse width 5ms
<b>Set Data</b>	0x0A	W	16 bit data, MSB first
<b>Get Data</b>	0x0B	R	16 bit data, MSB first

Note:

The EEPROM must be activated (wake up from standby) prior being used. The active command also initializes the EEPROM to its default state.

Note:

Each word must be erased before it can be written, a write command stores only a "1" to the EEPROM cell.  
Note: The commands "SET\_DATA" / "GET\_DATA" will increment the address pointer, except for the first execution after "SET\_ADDR".

## 11.5 I<sup>2</sup>C Example Sequences – EEPROM Wakeup / Standby

	ADDR	W/R	EEPROM_ACTIVE	
S	0x1B	0	0x01	P

	ADDR	W/R	EEPROM_STANDBY	
S	0x1B	0	0x00	P

## 11.6 I<sup>2</sup>C Example Sequences – EEPROM Block Erase / Block Write

	ADDR	W/R	EEPROM_ACTIVE	
S	0x1B	0	0x01	P

wait 1 ms

	ADDR	W/R	BLOCK_ERASE	
S	0x1B	0	0x04	P

wait 5 ms

	ADDR	W/R	SET_DATA	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0A	DATA	DATA	P

	ADDR	W/R	BLOCK_WRITE	
S	0x1B	0	0x05	P

wait 5 ms

	ADDR	W/R	STANDBY	
S	0x1B	0	0x00	P

## 11.7 I<sup>2</sup>C Example Sequences – EEPROM Sequential Erase/Write

	ADDR	W/R	EEPROM_ACTIVE	
S	0x1B	0	0x01	P

wait 1 ms

	ADDR	W/R	SET_ADDR	EEP_ADDR	
S	0x1B	0	0x09	ADDR	P

	ADDR	W/R	NORMAL_ERASE	
S	0x1B	0	0x02	P

wait 5 ms

	ADDR	W/R	SET_DATA	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0A	DATA	DATA	P

	ADDR	W/R	NORMAL_WRITE	
S	0x1B	0	0x03	P

wait 5 ms

	ADDR	W/R	SET_ADDR	EEP_ADDR	
S	0x1B	0	0x09	ADDR	P

	ADDR	W/R	NORMAL_ERASE	
S	0x1B	0	0x02	P

wait 5 ms

	ADDR	W/R	SET_DATA	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0A	DATA	DATA	P

	ADDR	W/R	NORMAL_WRITE	
S	0x1B	0	0x03	P

wait 5 ms

	ADDR	W/R	SET_ADDR	EEP_ADDR	
S	0x1B	0	0x09	ADDR	P

	ADDR	W/R	NORMAL_ERASE	
S	0x1B	0	0x02	P

wait 5 ms

	ADDR	W/R	SET_DATA	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0A	DATA	DATA	P

	ADDR	W/R	NORMAL_WRITE	
S	0x1B	0	0x03	P

wait 5 ms

	ADDR	W/R	SET_ADDR	EEP_ADDR	
S	0x1B	0	0x09	ADDR	P

	ADDR	W/R	NORMAL_ERASE	
S	0x1B	0	0x02	P

wait 5 ms

	ADDR	W/R	STANDBY	
S	0x1B	0	0x00	P

## 11.8 I<sup>2</sup>C Example Sequence – EEPROM Continuous Erase

	ADDR	W/R	EEPROM_ACTIVE	
S	0x1B	0	0x01	P

wait 1 ms

	ADDR	W/R	SET_ADDR	EEP_ADDR	
S	0x1B	0	0x09	ADDR	P

	ADDR	W/R	NORMAL_ERASE	
S	0x1B	0	0x02	P

wait 5 ms

	ADDR	W/R	SET_ADDR	EEP_ADDR	
S	0x1B	0	0x09	ADDR	P

	ADDR	W/R	NORMAL_ERASE	
S	0x1B	0	0x02	P

wait 5 ms

	ADDR	W/R	STANDBY	
S	0x1B	0	0x00	P

## 11.9 I<sup>2</sup>C Example Sequence – EEPROM Continuous Write

	ADDR	W/R	EEPROM_ACTIVE	
S	0x1B	0	0x01	P

wait 1 ms

	ADDR	W/R	SET_ADDR	EEP_ADDR	
S	0x1B	0	0x09	ADDR	P

	ADDR	W/R	SET_DATA	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0A	DATA	DATA	P

	ADDR	W/R	NORMAL_WRITE	
S	0x1B	0	0x03	P

wait 5 ms

	ADDR	W/R	SET_DATA	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0A	DATA	DATA	P

	ADDR	W/R	NORMAL_WRITE	
S	0x1B	0	0x03	P

wait 5 ms

	ADDR	W/R	STANDBY	
S	0x1B	0	0x00	P

## 11.10 I<sup>2</sup>C Example Sequence – EEPROM Sequential Read

	ADDR	W/R	EEPROM_ACTIVE	
S	0x1B	0	0x01	P

wait 1 ms

	ADDR	W/R	SET_ADDR	EEP_ADDR	
S	0x1B	0	0x09	ADDR	P

	ADDR	W/R	NORMAL_READ	
S	0x1B	0	0x06	P

	ADDR	W/R	GET_DATA		ADDR	W/R	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0B	Sr	0x1B	1	??	??	P

	ADDR	W/R	SET_ADDR	EEP_ADDR	
S	0x1B	0	0x09	ADDR	P

	ADDR	W/R	NORMAL_READ	
S	0x1B	0	0x06	P

	ADDR	W/R	GET_DATA		ADDR	W/R	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0B	Sr	0x1B	1	??	??	P

	ADDR	W/R	STANDBY	
S	0x1B	0	0x00	P

## 11.11 I<sup>2</sup>C Example Sequence – EEPROM Continuous Read

	ADDR	W/R	EEPROM_ACTIVE	
S	0x1B	0	0x01	P

wait 1 ms

	ADDR	W/R	SET_ADDR	EEP_ADDR	
S	0x1B	0	0x09	ADDR	P

	ADDR	W/R	NORMAL_READ	
S	0x1B	0	0x06	P

	ADDR	W/R	GET_DATA		ADDR	W/R	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0B	Sr	0x1B	1	??	??	P

	ADDR	W/R	GET_DATA		ADDR	W/R	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0B	Sr	0x1B	1	??	??	P

	ADDR	W/R	GET_DATA		ADDR	W/R	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0B	Sr	0x1B	1	??	??	P

	ADDR	W/R	GET_DATA		ADDR	W/R	DATA_MSB	DATA_LSB	
S	0x1B	0	0x0B	Sr	0x1B	1	??	??	P

	ADDR	W/R	STANDBY	
S	0x1B	0	0x00	P

## 11.12 I<sup>2</sup>C Example Sequence – Init and Read Thermopile Array

	ADDR	R/W	CONFIG_REG	WAKEUP	
S	0x1A	0	0x01	0x01	P

	ADDR	R/W	TRIM_REG1	MBIT_TRIM	
S	0x1A	0	0x03	0x0C	P

	ADDR	R/W	TRIM_REG2	BIAS_TRIML	
S	0x1A	0	0x04	0x0C	P

	ADDR	R/W	TRIM_REG3	BIAS_TRIMR	
S	0x1A	0	0x05	0x0C	P

	ADDR	R/W	TRIM_REG4	CLK_TRIM	
S	0x1A	0	0x06	0x14	P

	ADDR	R/W	TRIM_REG5	BPA_TRIML	
S	0x1A	0	0x07	0x0C	P

	ADDR	R/W	TRIM_REG6	BPA_TRIMR	
S	0x1A	0	0x08	0x0C	P

	ADDR	R/W	TRIM_REG7	PU_TRIM	
S	0x1A	0	0x09	0x88	P

	ADDR	R/W	CONFIG_REG	START / WAKEUP	
S	0x1A	0	0x01	0x09	P

	ADDR	R/W	STATUS_REG		ADDR	R/W	STATUS	
S	0x1A	0	0x02	Sr	0x1A	1	??	P

WAIT 30ms

	ADDR	R/W	STATUS_REG		ADDR	R/W	STATUS	
S	0x1A	0	0x02	Sr	0x1A	1	??	P

	ADDR	R/W	READ_DATA1		ADDR	R/W	PTAT1 MSB	PTAT1 LSB	P0,0 MSB	P0,0 LSB	...	Px,y MSB	Px,y LSB	
S	0x1A	0	0x0A	Sr	0x1A	1	??	??						P

	ADDR	R/W	READ_DATA2		ADDR	R/W	PTAT1 MSB	PTAT1 LSB	P0,0 MSB	P0,0 LSB	...	Px,y MSB	Px,y LSB	
S	0x1A	0	0x0B	Sr	0x1A	1	??	??						P

	ADDR	R/W	CONFIG_REG	SLEEP	
S	0x1A	0	0x01	0x00	P

## 12 Temperature Calculation

The object and ambient temperature can be calculated from the sensor output and the stored calibration data. The table below is showing an overview of the EEPROM.

16x16d	0x00	0x01	0x02	0x03	0x04	0x05	0x06	0x07	0x08	0x09	0x0A	0x0B	0x0C	0x0D	0x0E	0x0F
0	PixCmax (float)		PixCmax (float)						gradScale	GlobalGain			TN	epsilon	NrOfBpiv/Mask	DeadPixAdr
10	MBIT(user)	BIAS(user)	CLK(user)	BPA(user)	PU(user)	VddMeas(Th1)	VddMeas(Th2)				MBIT(calib)	BIAS(calib)	CLK(calib)	BPA(calib)	PU(calib)	
20													PTAT (Th1) (unsig)	PTAT (Th2) (un		
30					PTAT-gradient (float)	PTAT-offset (float)					Device ID			VddScGrad	VddScOff	
40	VddCompGrad stored as 12 bit sigend values															
90	VddCompOff stored as 12 bit sigend values															
A0	Th1 <sub>i</sub> / Grad <sub>i</sub> stored as 16 bit signed values															
F0	Th2 <sub>i</sub> / Offset <sub>i</sub> stored as 16 bit signed values															
2F0	P <sub>i</sub> stored as 16 bit unsigned values															
3F0																

All values are stored as unsigned 16 bit values in the little endian format unless they are specified otherwise. Grey marked areas are used during calibration or for future use and are Heimann Sensor reserved.

MBIT(calib), BIAS(calib), CLK(calib), BPA(calib) and PU(calib) are the settings for the registers that have been used during calibration (see chapter 11.3 on how to set them). MBIT(user), BIAS(user), CLK(user), BPA(user) and PU(user) are free to be set by the user. The temperature calculation is only valid if the same settings are used that have been set during calibration!

TN is the table number and has to match the given table number in the sample code.

GlobalGain, VDDTh1, VDDTh2, PTATTh1 and PTATTh2 are stored as 16 bit unsigned values.

VDDTH1 and VDDTH2 is the used supply voltage during calibration measured by the sensor itself and stored in Digits.

The corresponding order of  $ThGrad_{ij}$ ,  $ThOffset_{ij}$  and  $P_{ij}$  to the Pixel number is given by the following overview:

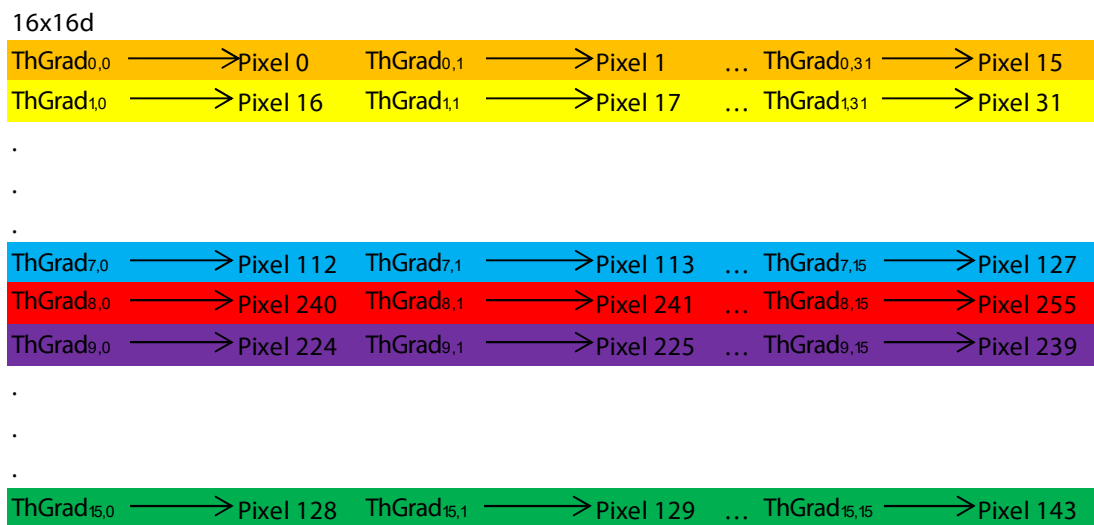


Figure 11: Readout Order 16x16d

The order of  $VddCompGrad_{ij}$  and  $VddCompOff_{ij}$  is similar to the electrical Offsets and have to be used block by block.  $VddCompGrad_{ij}$  and  $VddCompOff_{ij}$  are stored as 12 bit signed values with an offset of 0x800. Please check the sample code for a more detailed readout of the 12 bit values.

**16x16d**

VddCompGrad <sub>0,0</sub> →	Pixel 0	VddCompGrad <sub>0,1</sub> →	Pixel 1	...	VddCompGrad <sub>0,15</sub> →	Pixel 15	top half
VddCompGrad <sub>1,0</sub> →	Pixel 15	VddCompGrad <sub>1,1</sub> →	Pixel 16	...	VddCompGrad <sub>1,15</sub> →	Pixel 31	
VddCompGrad <sub>2,0</sub> →	Pixel 32	VddCompGrad <sub>2,1</sub> →	Pixel 33	...	VddCompGrad <sub>2,15</sub> →	Pixel 47	
VddCompGrad <sub>3,0</sub> →	Pixel 48	VddCompGrad <sub>3,1</sub> →	Pixel 49	...	VddCompGrad <sub>3,15</sub> →	Pixel 63	
VddCompGrad <sub>0,0</sub> →	Pixel 64	VddCompGrad <sub>0,1</sub> →	Pixel 65	...	VddCompGrad <sub>0,15</sub> →	Pixel 79	
.	.	.	.	.	.	.	
VddCompGrad <sub>3,0</sub> →	Pixel 112	VddCompGrad <sub>3,1</sub> →	Pixel 113	...	VddCompGrad <sub>3,15</sub> →	Pixel 127	bottom half
VddCompGrad <sub>4,0</sub> →	Pixel 240	VddCompGrad <sub>4,1</sub> →	Pixel 241	...	VddCompGrad <sub>4,15</sub> →	Pixel 255	
VddCompGrad <sub>5,0</sub> →	Pixel 224	VddCompGrad <sub>5,1</sub> →	Pixel 225	...	VddCompGrad <sub>5,15</sub> →	Pixel 239	
VddCompGrad <sub>6,0</sub> →	Pixel 208	VddCompGrad <sub>6,1</sub> →	Pixel 209	...	VddCompGrad <sub>6,15</sub> →	Pixel 223	
VddCompGrad <sub>7,0</sub> →	Pixel 192	VddCompGrad <sub>7,1</sub> →	Pixel 193	...	VddCompGrad <sub>7,15</sub> →	Pixel 207	
VddCompGrad <sub>4,0</sub> →	Pixel 176	VddCompGrad <sub>4,1</sub> →	Pixel 177	...	VddCompGrad <sub>4,15</sub> →	Pixel 191	
.	.	.	.	.	.	.	
VddCompGrad <sub>7,0</sub> →	Pixel 128	VddCompGrad <sub>7,1</sub> →	Pixel 129	...	VddCompGrad <sub>7,15</sub> →	Pixel 143	

Figure 10: Readout of VDDCompGrad 16x16d

## 12.1 Ambient Temperature

The ambient temperature ( $T_a$ ) is calculated from the average measured PTAT value, the  $PTAT_{gradient}$  and the  $PTAT_{offset}$ . It is recommended to use a stack buffer for the PTAT values in order to get a more stable ambient temperature result.

$$T_a = PTAT_{av} \cdot PTAT_{gradient} + PTAT_{offset} \quad (\text{Value is given back in } \mu\text{K})$$

where:

$PTAT_{gradient}$  is the gradient of the PTAT stored in the EEPROM as a float value

$PTAT_{offset}$  is the offset of the PTAT stored in the EEPROM as a float value

$PTAT_{av} = \frac{\sum_{i=0}^3 PTAT_i}{4}$  is the average measured PTAT value

## 12.2 Thermal Offset

The thermal offset of the sensor needs to be subtracted for each pixel to compensate for any thermal drifts.

$$V_{ij\_Comp} = V_{ij} - \frac{ThGrad_{ij} \cdot Ta}{2gradScale} - ThOffset_{ij}$$

where:

$ij$	represents the row (i) and column (j) of the pixel
$V_{ij\_Comp}$	is the thermal offset compensated voltage
$V_{ij}$	is the raw pixel data (digital), readout from the RAM
$ThGrad_{ij}$	is the thermal gradient, stored in the EEPROM from 0x40 to 0x7F
$ThOffset_{ij}$	is the thermal offset, stored in the EEPROM from 0x80 to 0xBF
$gradScale$	is the scaling coefficient for the thermal gradient stored in the EEPROM

## 12.3 Electrical Offset

The electrical offset is used to compensate changes in the supply voltage. This compensation is only a subtraction, so it can be done before or after the thermal offset compensation (here done afterwards). It is recommended to use an electrical offset stack in order to get a more stable electrical offset result and a more stable temperature result at the end. The electrical offsets should be sampled every 8<sup>th</sup> to 10<sup>th</sup> frame.

The compensation for the top half is done by using the following formula:

$$V_{ij\_Comp} * = V_{ij\_Comp} - elOffset[(j + i \cdot 16) \% 64]$$

and the bottom half analogue with this formula:

$$V_{ij\_Comp} * = V_{ij\_Comp} - elOffset[(j + i \cdot 16) \% 64 + 64]$$

where:

$ij$	represents the row (i) and column (j) of the pixel and electrical offset
$V_{ij\_Comp} *$	is the thermal and electrical offset compensated voltage
$V_{ij\_Comp}$	is the thermal offset compensated voltage
$elOffset_{ij}$	is the electrical offset belonging to Pixel ij
$i \% 64$	is the rest of the integer division of i by 64 (e.g. $68 \% 64 = 2$ ) ("modulo")

## 12.4 VDD Compensation

A supply voltage compensation called VddComp is used to take care of supply voltage changes. In order to use this compensation the supply voltage of the sensor (Vdd) has to be measured by the sensor from time to time by setting the configuration register and the average of Vdd 1 and Vdd 2 is resulting in Vdd (similar like  $PTAT_{av}$ ). It is recommended to use a VDD stack buffer in order to get a more stable VDD value. The stack should be similar to the PTAT stack.

The compensation for the top half is done by using the following formula:

$$VDD_{av} = \frac{\sum_{i=0}^3 VDD_i}{4}$$

$$V_{ijVDDComp} = V_{ijComp} * \frac{\left( \frac{VddCompGrad[(j + i \cdot 16)\%64] \cdot PTAT_{av} + VddCompOff[(j + i \cdot 16)\%64]}{2^{VDDScGrad}} \right)}{2^{VDDScOff}}$$

$$\cdot \left( VDD_{av} - VDD_{TH1} - \left( \frac{VDD_{TH2} - VDD_{TH}}{PTAT_{TH2} - PTAT_{TH1}} \right) \cdot (PTAT_{av} - PTAT_{TH1}) \right)$$

And the bottom half analogue with this formula:

$$V_{ijVDDComp} = V_{ijComp} * \frac{\left( \frac{VddCompGrad[(j + i \cdot 16)\%64 + 64] \cdot PTAT_{av} + VddCompOff[(j + i \cdot 16)\%64 + 64]}{2^{VDDScGrad}} \right)}{2^{VDDScOff}}$$

$$\cdot \left( VDD_{av} - VDD_{TH1} - \left( \frac{VDD_{TH} - VDD_{TH}}{PTAT_{TH2} - PTAT_{TH1}} \right) \cdot (PTAT_{av} - PTAT_{TH}) \right)$$

where:

$ij$	represents the row (i) and column (j) of the pixel
$V_{ijVDDComp}$	is the Vdd compensated voltage
$V_{ijComp} *$	is the thermal and electrical offset compensated voltage
$VddComGrad[ij]$	is the VddComp gradient belonging to Pixel ij
$VddComOff[ij]$	is the VddComp offset belonging to Pixel ij
$i\%64$	is the rest of the integer division of i by 64 (e.g. $66\%64=2$ ) ("modulo")
$VDD_{av}$	is the average measured supply voltage of the sensor in Digits
$VddScGrad$	is a scaling coefficient and stored in the EEPROM 0x3E

$VddScOff$	is a scaling coefficient and stored in the EEPROM 0x3F
$VDD_{TH1}$	is the supply voltage during calibration 1 stored in the EEPROM 0x25
$VDD_{TH2}$	is the supply voltage during calibration 2 stored in the EEPROM 0x26
$PTAT_{TH1}$	is the PTAT value of calibration 1 stored in the EEPROM 0x2C
$PTAT_{TH2}$	is the PTAT value of calibration 2 stored in the EEPROM 0x2D

## 12.5 Object Temperature

The calculation of the object temperature is done by using a look-up table and doing a bi-linear interpolation, the matching table is given by the table number (TN). The table is supplied in a separate file named "Table.c". If you do not have the file, please ask Heimann Sensor for support.

The sensitivity coefficients ( $PixC_{ij}$ ) are calculated in the following way:

$$PixC_{ij} = \left( \frac{P_{ij} \cdot (PixC_{max} - PixC_{min})}{65535} + PixC_{min} \right) \cdot \frac{\epsilon}{100} \cdot \frac{GlobalGain}{10000}$$

where:

$PixC_{ij}$	is the sensitivity coefficient for each pixel
$P_{ij}$	is the stored sensitivity coefficient scaled to 16 bit
$PixC_{min}$	is the minimum sensitivity coefficient, used for scaling
$PixC_{max}$	is the maximum sensitivity coefficient, used for scaling
$\epsilon$	is the emissivity factor
$GlobalGain$	is a factor for fine tuning of the sensitivity for all Pixel

Leading to a compensation of the pixel voltage

$$V_{ij\_PixC} = \frac{V_{ij\_VDDcomp} \cdot PCSCALEVAL}{PixC_{ij}}$$

where:

$V_{ij\_PixC}$  is the sensitivity compensated IR voltage

$PCSCALEVAL$  is a defined scaling coefficient, typically set to  $1 \cdot 10^8$

## 13 Example Calculation

$$PTAT = 32357 \text{ Digits}$$

$$PTAT_{gradient} = 0.046 \text{ dK/Digit}$$

$$V_{00} = 34435 \text{ Digits}$$

$$gradScale = 15$$

$$ThGrad_{00} = 56693 \xrightarrow{\text{sign check}} -8842$$

$$ThOffset_{00} = 44$$

$$elOffset_{00} = 35000$$

$$PixC_{00} = 1.1 \cdot 10^8$$

$$PCSCALEVAL = 1.1 \cdot 10^8$$

### Calculation of ambient temperature:

$$Ta = PTAT \cdot PTAT_{gradient} + PTAT_{offset} = 32357 \cdot 0.046 + 1511.6 \text{ dK} = 3000 \text{ dK}$$

### Compensation of thermal offset:

$$V_{00\_comp} = V_{00} - \frac{ThGrad_{00} \cdot Ta}{2^{gradscale}} - ThOffset_{00} = -\frac{-8842 \cdot 3000}{2^{15}} - 44 = 35200$$

### Compensation of electrical offset:

$$V_{00\_comp}^* = V_{00\_comp} - elOffset_{00} = 35200 - 35000 = 200$$

### 13.1 Example Look-up Table

Look-up table, TO values are given in dK				
TA[dK]/dig	2882	3032	3182	3332
-64	1494	2128	2491	2775
-32	2466	2692	2898	3091
0	2882	3032	3182	3332
32	3170	3285	3406	3530
64	3396	3491	3592	3699
96	3584	3665	3754	3848
128	3746	3818	3897	3981
160	3890	3954	4025	4102
192	4019	4078	4143	4214
224	4137	4191	4251	4317
256	4246	4296	4351	4413
288	4347	4393	4445	4503
320	4441	4485	4534	4588

$$V_{00\_Comp} = \frac{200 \cdot 1 \cdot 10^8}{1.1 \cdot 10^8}$$

Ta was calculated before to 3000 dK.

The matching region in the look-up table is already marked yellow, the bi-linear interpolation is leading to an object temperature of 4026 dK = (4026dK-2732dK)/10 = 129.4 °C.

# HTPA16x16dR2L2.1/0.8F5.0

02.03.2026(Revision 20)

Page 31 of 33



The matching look-up table has to be taken from the "Table.c" file. Here is just shown an exemplary data for one optic.

dig 1 Tab(dK)	2782	2882	2982	3082	3182	3282	3382
-512					1742	2002	2202
-448					2094	2284	2442
-384					2230	2420	2534
-320					2534	2671	2797
-256					2697	2822	2938
-192	2287	2444	2587	2717	2839	2954	3065
-128	2618	2812	2975	3125	3252	3364	3463
-64	2842	2755	2865	2972	3078	3182	3285
0	2762	2882	2982	3082	3182	3282	3382
64	2908	2998	3089	3183	3278	3373	3473
128	3018	3101	3187	3276	3368	3462	3558
192	3121	3197	3278	3363	3452	3544	3638
256	3216	3286	3363	3445	3531	3621	3715
320	3305	3370	3443	3522	3606	3695	3787
384	3387	3449	3519	3595	3677	3764	3856
448	3465	3524	3590	3664	3745	3831	3922
512	3538	3595	3659	3731	3810	3895	3986
576	3609	3662	3724	3794	3872	3957	4047
640	3676	3727	3787	3855	3932	4016	4106
704	3740	3788	3847	3914	3990	4073	4163
768	3802	3849	3904	3971	4046	4128	4216
832	3861	3905	3960	4025	4100	4182	4271
896	3918	3960	4014	4078	4152	4233	4322
960	3973	4014	4066	4129	4202	4284	4372
1024	4026	4065	4117	4179	4251	4332	4421
1088	4077	4115	4166	4227	4299	4380	4469
1152	4127	4164	4213	4274	4345	4426	4515
1216	4175	4211	4260	4320	4391	4471	4560
1280	4222	4257	4305	4364	4435	4515	4604
1344	4268	4302	4349	4408	4478	4558	4647
1408	4312	4345	4391	4450	4520	4600	4689
1472	4355	4388	4433	4492	4561	4641	4730
1536	4396	4428	4474	4532	4601	4681	4770
1600	4436	4467	4514	4571	4640	4720	4809
1664	4474	4505	4553	4610	4679	4758	4848
1728	4510	4540	4588	4645	4714	4793	4882
1792	4545	4575	4623	4680	4749	4828	4917
1856	4579	4608	4656	4713	4782	4861	4950
1920	4612	4640	4688	4745	4814	4893	4982
1984	4645	4672	4720	4777	4846	4925	5014
2048	4677	4704	4752	4809	4878	4957	5046
2112	4708	4735	4783	4840	4909	4988	5077
2176	4739	4766	4814	4871	4940	5019	5108
2240	4769	4796	4844	4901	4970	5049	5138
2304	4798	4825	4873	4930	5000	5079	5168
2368	4827	4854	4902	4959	5029	5108	5197
2432	4855	4882	4930	4987	5057	5136	5225
2496	4883	4910	4958	5015	5085	5164	5254
2560	4911	4938	4986	5043	5113	5192	5283
2624	4939	4966	5014	5071	5141	5220	5309
2688	4967	4994	5042	5099	5169	5248	5338
2752	4995	5022	5070	5127	5197	5276	5365
2816	5023	5050	5098	5155	5225	5304	5393
2880	5051	5078	5126	5183	5253	5332	5421
2944	5079	5106	5154	5211	5281	5360	5449
3008	5107	5134	5182	5239	5309	5388	5477
3072	5135	5162	5210	5267	5337	5416	5505
3136	5163	5190	5238	5295	5365	5444	5534
3200	5191	5218	5266	5323	5393	5472	5563
3264	5219	5246	5294	5351	5421	5500	5589
3328	5247	5274	5322	5379	5449	5528	5617
3392	5275	5302	5350	5407	5477	5556	5645
3456	5303	5330	5378	5435	5505	5584	5673
3520	5331	5358	5406	5463	5533	5612	5701
3584	5359	5386	5434	5491	5561	5640	5729
3648	5387	5414	5462	5519	5589	5668	5757
3712	5415	5442	5490	5547	5617	5696	5785
3776	5443	5470	5518	5575	5645	5724	5813
3840	5471	5498	5546	5603	5673	5752	5841
3904	5500	5527	5575	5632	5702	5781	5870
3968	5528	5555	5603	5660	5730	5809	5898
4032	5556	5583	5631	5688	5758	5837	5926
4096	5584	5611	5659	5716	5786	5865	5954
4160	5612	5639	5687	5744	5814	5893	5982
4224	5640	5667	5715	5772	5842	5921	6010
4288	5668	5695	5743	5800	5870	5949	6038
4352	5696	5723	5771	5828	5898	5977	6066
4416	5724	5751	5800	5857	5927	6006	6095
4480	5752	5779	5827	5884	5954	6033	6122
4544	5780	5807	5855	5912	5982	6061	6150
4608	5808	5835	5883	5940	6010	6089	6178
4672	5836	5863	5911	5968	6038	6117	6206
4736	5864	5891	5939	5996	6066	6145	6234
4800	5892	5919	5967	6024	6094	6173	6262
4864	5920	5947	5995	6052	6122	6201	6290
4928	5948	5975	6023	6080	6150	6229	6318
4992	5976	6003	6051	6108	6178	6257	6346
5056	6004	6031	6079	6136	6206	6285	6374
5120	6032	6059	6107	6164	6234	6313	6402
5184	6060	6087	6135	6192	6262	6341	6430
5248	6088	6115	6163	6220	6290	6369	6458
5312	6116	6143	6191	6248	6318	6397	6486
5376	6144	6171	6219	6276	6346	6425	6514
5440	6172	6199	6247	6304	6374	6453	6542
5504	6200	6227	6275	6332	6402	6481	6570
5568	6228	6255	6303	6360	6430	6509	6600
5632	6256	6283	6331	6388	6458	6537	6628
5696	6284	6311	6359	6416	6486	6565	6657
5760	6312	6339	6387	6444	6514	6593	6682
5824	6340	6367	6415	6472	6542	6621	6710
5888	6368	6395	6443	6500	6570	6649	6738
5952	6396	6423	6471	6528	6598	6677	6766
6016	6424	6451	6499	6556	6626	6705	6794
6080	6452	6479	6527	6584	6654	6733	6822
6144	6480	6507	6555	6612	6682	6761	6850
6208	6508	6535	6583	6640	6710	6789	6878
6272	6536	6563	6611	6668	6738	6817	6906
6336	6564	6591	6639	6696	6766	6845	6934
6400	6592	6619	6667	6724	6794	6873	6962
6464	6620	6647	6695	6752	6822	6901	6990
6528	6648	6675	6723	6780	6850	6929	7018
6592	6676	6703	6751	6808	6878	6957	7046
6656	6704	6731	6779	6836	6906	6985	7074
6720	6732	6759	6807	6864	6934	7013	7102
6784	6760	6787	6835	6892	6962	7041	7130

6848	6421	6431	6462	6514	6584	6673	6777
6912	6437	6447	6478	6530	6600	6689	6794
6976	6453	6463	6494	6546	6616	6705	6810
7040	6468	6479	6510	6562	6632	6721	6826
7104	6485	6495	6526	6578	6648	6737	6842
7168	6501	6511	6542	6594	6664	6753	6858
7232	6517	6526	6557	6609	6679	6768	6873
7296	6532	6542	6573	6625	6695	6784	6889
7360	6548	6557	6588	6640	6710	6800	6905
7424	6563	6572	6603	6655	6725	6814	6919
7488	6578	6588	6619	6671	6741	6831	6936
7552	6593	6603	6634	6686	6756	6846	6953
7616	6609	6618	6649	6701	6771	6861	6968
7680	6624	6633	6664	6716	6786	6876	6984
7744	6639	6648	6679	6731	6801	6891	6999
7808	6654	6663	6694	6746	6816	6906	7014
7872	6669	6677	6708	6760	6830	6920	7029
7936	6683	6692	6723	6775	6845	6935	7044
8000	6698	6707	6737	6789	6859	6949	7058
8064	6712	6721	6752	6804	6874	6964	7074
8128	6727	6735	6766	6818	6888	6978	7089
8192	6741	6750	6781	6833	6903	6993	7104
8256	6756	6764	6795	6847	6917	7007	7118
8320	6770	6778	6809	6861	6931	7021	7133
8384	6784	6792	6823	6875	6945	7035	7147
8448	6798	6806	6837	6889	6959	7049	7162
8512	6812	6820	6851	6903	6973	7063	7177
8576	6826	6834	6865	6917	6987	7077	7191
8640	6840	6848	6879	6931	7001	7091	7205
8704	6854	6862	6893	6945	7015	7105	7219
8768	6868	6876	6907	6959	7029	7119	7233
8832	6881	6889	6920	6972	7042	7132	7247
8896	6895	6903	6934	6986	7056	7146	7261
8960	6908	6916	6947	7000	7070	7160	7275
9024	6922	6930	6961	7013	7083	7173	7289
9088	6935	6943	6974	7026	7096	7186	7303
9152	6949	6957	6988	7040	7110	7200	7317
9216	6962	6970	7001	7053	7123	7213	7329
9280	6975	6983	7014	7066	7136	7226	7343
9344	6988	6996	7027	7079	7149	7239	7356
9408	7001	7009	7040	7103	7173	7263	7370
9472	7015	7022	7053	7116	7186	7276	7383
9536	7028	7035	7066	7129	7199	7289	7396
9600	7040	7048	7079	7142	7212	7302	7410
9664	7052	7060	7091	7154	7224	7314	

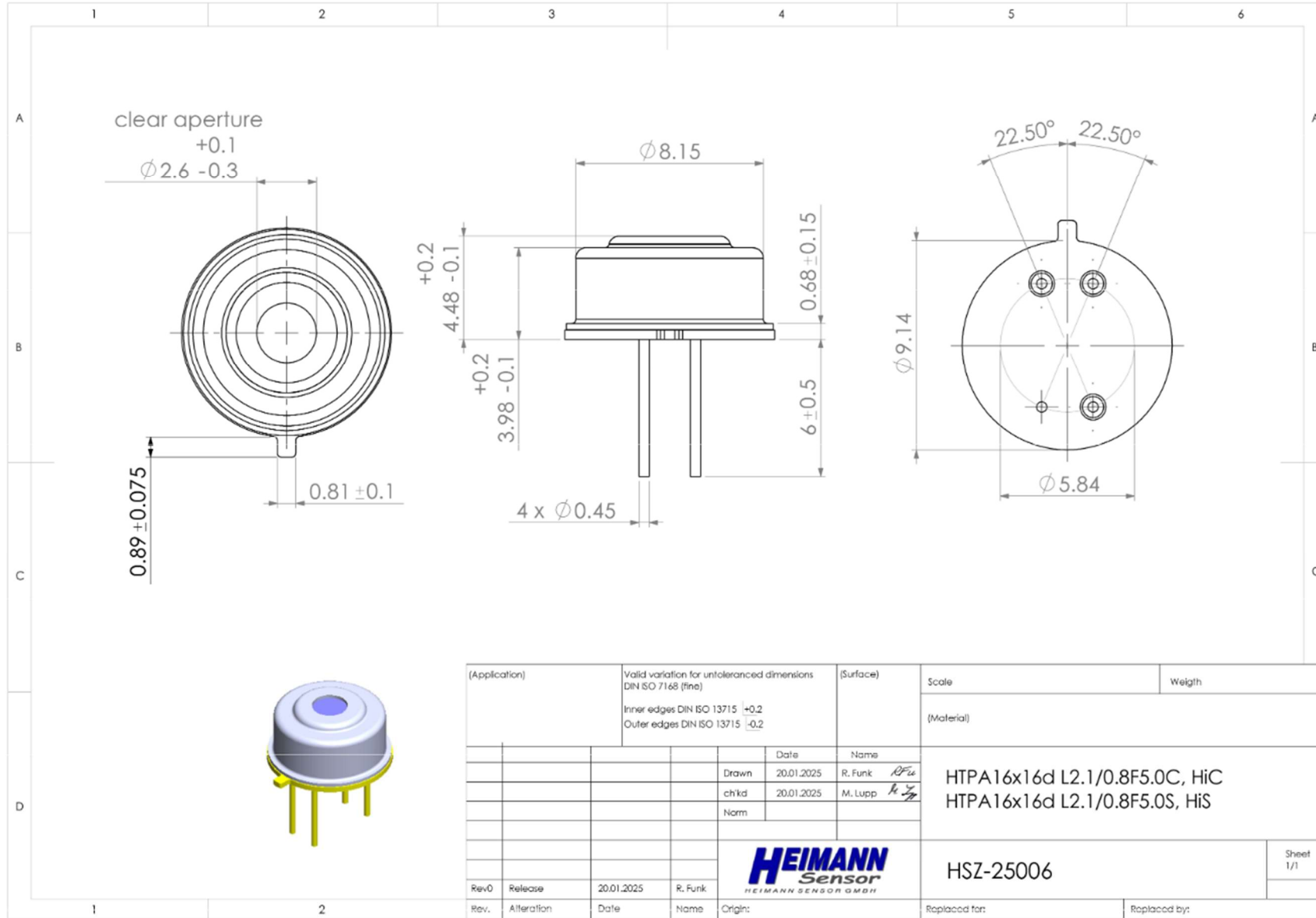
## 14 Order Code Chart

HTPA16x16d	R2	<b>L1.0/0.8</b>	F5.0	Hi	<b>A</b>	<b>(USB)</b>
HTPA16x16d	R2	<b>L1.0/0.8</b>	F5.0	Hi	<b>A</b>	<b>(UDP)</b>
HTPA16x16d	R2	<b>L1.0/0.8</b>	F5.0	Hi	<b>M</b>	<b>(UDP)</b>
HTPA16x16d	R2	<b>L1.0/0.8</b>	F5.0	Hi	<b>C</b>	
HTPA16x16d	R2	<b>L1.6/0.8</b>	F5.0	Hi	<b>A</b>	<b>(USB)</b>
HTPA16x16d	R2	<b>L1.6/0.8</b>	F5.0	Hi	<b>A</b>	<b>(UDP)</b>
HTPA16x16d	R2	<b>L1.6/0.8</b>	F5.0	Hi	<b>M</b>	<b>(UDP)</b>
HTPA16x16d	R2	<b>L1.6/0.8</b>	F5.0	Hi	<b>C</b>	
HTPA16x16d	R2	<b>L2.1/0.8</b>	F5.0	Hi	<b>A</b>	<b>(USB)</b>
HTPA16x16d	R2	<b>L2.1/0.8</b>	F5.0	Hi	<b>A</b>	<b>(UDP)</b>
HTPA16x16d	R2	<b>L2.1/0.8</b>	F5.0	Hi	<b>M</b>	<b>(UDP)</b>
HTPA16x16d	R2	<b>L2.1/0.8</b>	F5.0	Hi	<b>C</b>	
HTPA16x16d	R2	<b>L5.0/1.0</b>	F7.7	Hi	<b>A</b>	<b>(USB)</b>
HTPA16x16d	R2	<b>L5.0/1.0</b>	F7.7	Hi	<b>A</b>	<b>(UDP)</b>
HTPA16x16d	R2	<b>L5.0/1.0</b>	F7.7	Hi	<b>M</b>	<b>(UDP)</b>
HTPA16x16d	R2	<b>L5.0/1.0</b>	F7.7	Hi	<b>C</b>	

**Bold: Selectable options**

Regular: Fixed/Not selectable

# 15 Outer Dimension



(Application)	Valid variation for untoleranced dimensions DIN ISO 7168 (fine)	(Surface)	Scale	Weight
	Inner edges DIN ISO 13715 $-0.2$ Outer edges DIN ISO 13715 $-0.2$		(Material)	
		Date	Name	
		Drawn 20.01.2025	R. Funk <i>R.F.</i>	HTPA16x16d L2.1/0.8F5.0C, HiC HTPA16x16d L2.1/0.8F5.0S, HiS
		ch'kd 20.01.2025	M. Lupp <i>M.L.</i>	
		Norm		
Rev0	Release	20.01.2025	R. Funk	HSZ-25006
Rev.	Alteration	Date	Name	
			Origin:	Replaced for:
				Replaced by:



Sheet 1/1